RoHS

COMPLIANT

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Vishay Semiconductors

High Power Infrared Emitting Diode, 850 nm, Surface Emitter Technology



DESCRIPTION

As part of the <u>SurfLightTM</u> portfolio, the VSMY9857535 is an infrared, 850 nm emitting diode based on surface emitter technology with high radiant power and high speed, molded in low thermal resistance SMD package with lens. A 35 mil chip provides outstanding radiant intensity and allows DC operation of the device up to 1.0 A.

FEATURES

- · Package type: surface mount
- Package form: high power SMD with lens
- Dimensions (L x W x H in mm): 3.85 x 3.85 x 1.51
- Peak wavelength: $\lambda_p = 850 \text{ nm}$
- · High radiant power
- · High radiant intensity
- Angle of half intensity: $\varphi = \pm 75^{\circ}$
- Designed for high drive currents: up to 1.0 A (DC) and up to 5 A pulses
- Low thermal resistance: R_{thJP} = 10 K/W
- Floor life: 168 h, MSL 3, according to J-STD-020
- · Lead (Pb)-free reflow soldering
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

APPLICATIONS

- Infrared illumination for CMOS cameras (CCTV, 3D gaming)
- · Machine vision
- Bio identification

PRODUCT SUMMARY				
COMPONENT	I _e (mW/sr)	φ (deg)	λ _p (nm)	t _r (ns)
VSMY9857535	180	± 75	850	30

Note

Test conditions see table "Basic Characteristics"

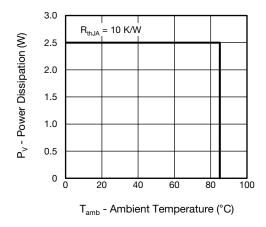
ORDERING INFORMATION				
ORDERING CODE	PACKAGING	REMARKS	PACKAGE FORM	
VSMY9857535	Tape and reel	MOQ: 600 pcs, 600 pcs/reel	High power with lens	

Note

MOQ: minimum order quantity

ABSOLUTE MAXIMUM RATINGS (T _{amb} = 25 °C, unless otherwise specified)					
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT	
Reverse voltage		V _R	5	V	
Forward current		I _F	1	Α	
Peak forward current	$t_p/T = 0.5, t_p = 100 \mu s$	I _{FM}	2	Α	
Surge forward current	t _p = 100 μs	I _{FSM}	5	А	
Power dissipation		P _V	2.5	W	
Junction temperature		Tj	115	°C	
Operating temperature range		T _{amb}	-40 to +85	°C	
Storage temperature range		T _{stg}	-55 to +100	°C	
Soldering temperature	According to Fig. 10, J-STD-20	T _{sd}	260	°C	
Thermal resistance junction / pin	JESD 51	R_{thJP}	10	K/W	







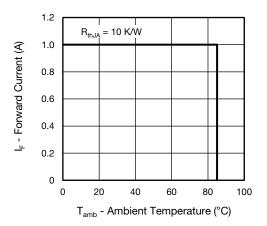


Fig. 2 - Forward Current Limit vs. Ambient Temperature

BASIC CHARACTERISTICS (T _{amb} = 25 °C, unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Forward voltage	$I_F = 1 \text{ A}, t_p = 20 \text{ ms}$	V _F	-	1.8	2.5	V
	$I_F = 5 \text{ A}, t_p = 100 \mu \text{s}$	V _F	-	2.7	-	V
Temperature coefficient of V _F	I _F = 100 mA	TK _{VF}	-	-1.5	-	mV/K
Reverse current	V _R = 5 V	I _R	Not designed for reverse operation			μA
Radiant intensity	$I_F = 1 \text{ A}, t_p = 20 \text{ ms}$	l _e	100	180	-	mW/sr
	$I_F = 5 \text{ A}, t_p = 100 \mu \text{s}$	l _e	-	900	-	mW/sr
Radiant power	$I_F = 1 \text{ A}, t_p = 20 \text{ ms}$	φ _e	-	630	-	mW
Temperature coefficient of φ _e	I _F = 100 mA	TKφ _e	-	-0.13	-	%/K
Angle of half intensity		φ	-	± 75	-	deg
Peak wavelength	I _F = 1 A	λ_{p}	-	850	-	nm
Spectral bandwidth	I _F = 1 A	Δλ	-	35	-	nm
Temperature coefficient of λ_p	I _F = 100 mA	TKλ _p	-	0.2	-	nm/K
Rise time	I _F = 1 A	t _r	-	30	-	ns
Fall time	I _F = 1 A	t _f	-	30	-	ns

BASIC CHARACTERISTICS (T_{amb} = 25 °C, unless otherwise specified)

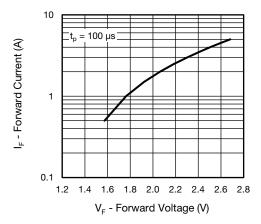


Fig. 3 - Forward Current vs. Forward Voltage

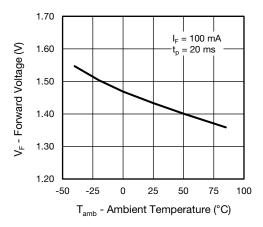


Fig. 4 - Forward Voltage vs. Ambient Temperature

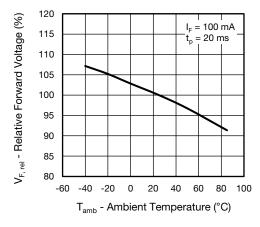


Fig. 5 - Relative Forward Voltage vs. Ambient Temperature

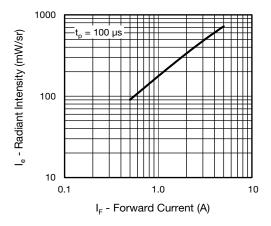


Fig. 6 - Radiant Intensity vs. Forward Current

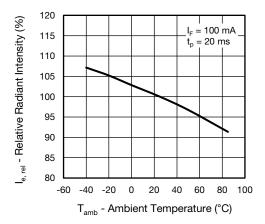


Fig. 7 - Relative Radiant Intensity vs. Ambient Temperature

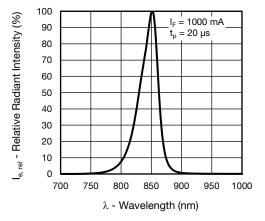


Fig. 8 - Relative Radiant Intensity vs. Wavelength



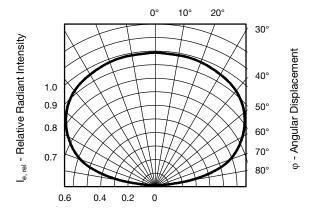
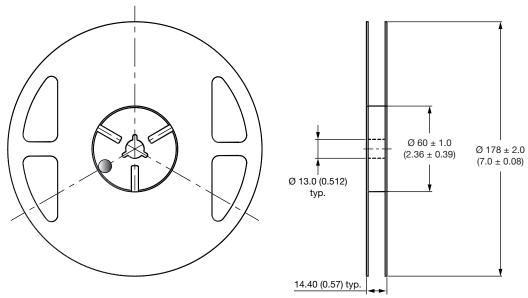


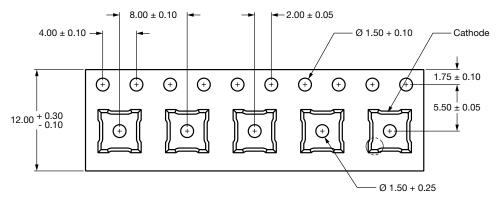
Fig. 9 - Relative Radiant Intensity vs. Angular Displacement

TAPING DIMENSIONS in millimeters

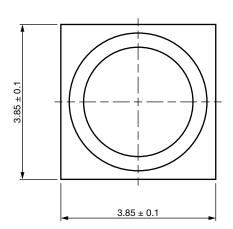


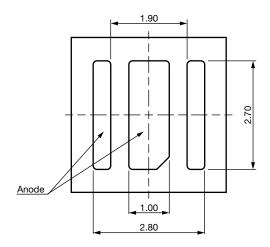
Notes

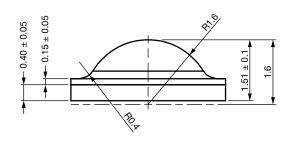
- Empty component pockets sealed with top cover tape.
- 7 inch reel 600 pieces per reel.
- The maximum number of consecutive missing lamps is two.
- In accordance with ANSI / EIA 481-1-A-1994 specifications.

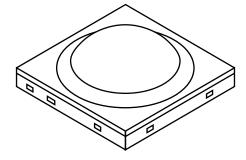


PACKAGE DIMENSIONS in millimeters





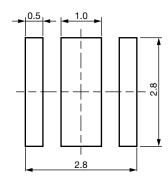




Notes

- Tolerance is \pm 0.10 mm (0.004") unless otherwise noted.
- Specifications are subject to change without notice.

SOLDER PAD PROPOSAL



SOLDER PROFILE

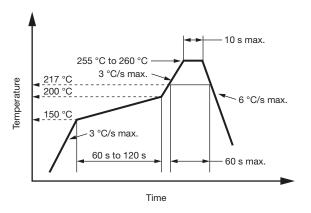


Fig. 10 - Lead (Pb)-free Reflow Solder Profile According to J-STD-020

DRYPACK

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

FLOOR LIFE

Floor life (time between soldering and removing from MBB) must not exceed the time indicated on MBB label:

Floor life: 168 h

Conditions: T_{amb} < 30 °C, RH < 60 %

Moisture sensitivity level 3, according to J-STD-020B

DRYING

In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or label. Devices taped on reel dry using recommended conditions 192 h at 40 $^{\circ}$ C (+ 5 $^{\circ}$ C), RH < 5 $^{\circ}$ M.



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Vishay

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